Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L4	10	card$1 same (paper adj core) same (chip$1 or module$1 or IC or (integrated adj circuit$1)) same (seal$4 or laminat$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/02/08 13:53
L9	34	card$1 and (paper adj core) and (chip$1 or module$1 or IC or (integrated adj circuit$1)) and (seal$4 or laminat$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/02/08 14:37
L10	31	card$1 and (paper adj core) and (chip$1 or module$1 or IC or (integrated adj circuit$1)) and (seal$4 or laminat$4) and adhe$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/02/08 14:50
L20	46	card$1 same (paper) same (chip$1 or module$1 or IC or (integrated adj circuit$1)) same (adhe$4 or cohe$4) and strong$4 and (seal$4 or laminat$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/02/08 15:56
L22	17	card$1 same (paper) same (chip$1 or module$1 or IC or (integrated adj circuit$1)) same (adhe$4 or cohe$4) and strong$4 same (seal$4 or laminat$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/02/08 16:04
L23	4	card$1 same (paper) same (chip$1 or module$1 or IC or (integrated adj circuit$1)) same (adhe$4 or cohe$4) same strong$4 same (seal$4 or laminat$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/02/08 16:06
L26	71	card$1 same (paper) same (chip$1 or module$1 or IC or (integrated adj circuit$1)) same (adhe$4 or cohe$4) same(seal$4 or laminat$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/02/08 17:04
L27	23	card$1 same (paper) same (chip$1 or module$1 or IC or (integrated adj circuit$1)) same (adhe$4 or cohe$4) same(seal$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/02/08 17:05
L28	4	card$1 same (paper adj core$1) same (chip$1 or module$1 or IC or (integrated adj circuit$1)) same (adhe$4 or cohe$4) same (seal$4 or laminat$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/02/08 17:05